





DMC3028LSD

**30V COMPLEMENTARY DUAL ENHANCEMENT MODE MOSFET** 

#### **Product Summary**

Device	V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> T <sub>A</sub> = 25°C
01	Q1 30V	$28 \mathrm{m}\Omega @ \mathrm{V}_\mathrm{GS}$ = 10V	7.1A
QI	30 V	45mΩ @ V <sub>GS</sub> = 4.5V	5.6A
02	2017	$25m\Omega @ V_{GS}=-10V$	-7.4A
Q2	-307	41mΩ @ V <sub>GS</sub> = -4.5V	-5.7A

### **Description and Applications**

This new generation complementary dual MOSFET features low onresistance and fast switching, making it ideal for high efficiency power management applications.

- Motor control
- Backlighting
- **DC-DC Converters**
- Power management functions

#### **Features and Benefits**

- Low on-resistance
- Fast switching speed
- "Green" Component and RoHS Compliant (Note 1)

#### **Mechanical Data**

- Case: SO-8 .
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0 (Note 1)
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram •
- Terminals: Finish Matte Tin annealed over Copper lead frame. . Solderable per MIL-STD-202, Method 208
- Weight: 0.074 grams (approximate)





Q2 P-Channel

#### Ordering Information (Note 1)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DMC3028LSD-13	C3028LD	13	12	2,500

1. Diodes, Inc. defines "Green" products as those which are Eu RoHS compliant and contain no halogens or antimony compounds; further information about Diodes Inc.'s "Green" Policy can be found on our website. For packaging details, go to our website Note:

### Marking Information



) | | = Manufacturer's Marking C3028LD = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 09 = 2009) WW = Week (01-52)





# **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

	Characteristic		Symbol	N-Channel - Q1	P-Channel - Q2	Units
Drain-Source Voltage			V <sub>DSS</sub>	30	-30	V
Gate-Source Voltage	Gate-Source Voltage			±20	±20	V
		(Notes 3 & 5)		7.1	-7.4	
Continuous Drain Current	$\lambda = 10 \lambda$	T <sub>A</sub> = 70°C (Notes 3 & 5)	ID	5.7	-5.9	A
Continuous Drain Current	$v_{GS} = 10v$	(Notes 2 & 5)		5.5	-5.8	
		(Notes 2 & 6)		6.6	-6.8	
Pulsed Drain Current $V_{GS} = 10V$ (Notes 4 & 5)		(Notes 4 & 5)	I <sub>DM</sub>	34	-36	А
Continuous Source Current (Body diode) (Notes 3 & 5)		(Notes 3 & 5)	Is	3.5	-3.5	А
Pulsed Source Current (Bod	y diode)	(Notes 4 & 5)	I <sub>SM</sub>	34	-36	A

## Thermal Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic		Symbol	N-Channel - Q1	P-Channel - Q2	Unit		
Power Dissipation Linear Derating Factor	(Notes 2 & 5)	PD	1	1.3 10			
Power Dissipation Linear Derating Factor	(Notes 2 & 6)	PD	1	W mW/°C			
Power Dissipation Linear Derating Factor	(Notes 3 & 5)	PD	2 1	W mW/°C			
Thermal Resistance, Junction to Ambient	(Notes 2 & 5) (Notes 2 & 6) (Notes 3 & 5)	R <sub>θJA</sub>	100 70 60		°C/W		
Thermal Resistance, Junction to Lead	(Notes 5 & 7)	R <sub>θJL</sub>	51 46		°C/W		
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to	°C				

2. For a device surface mounted on 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is Notes: measured when operating in a steady-state condition. 3. Same as note (2), except the device is measured at  $t \le 10$  sec.

4. Same as note (2), except the device is pulsed with D= 0.02 and pulse width 300 µs. The pulse current is limited by the maximum junction temperature.

5. For a dual device with one active die.

6. For a device with two active die running at equal power.

7. Thermal resistance from junction to solder-point (at the end of the drain lead).







**Pulse Power Dissipation** 





Electrical Characteristics – Q1 N-C	hannel	@T <sub>A</sub> = 25	°C unless c	otherwise sp	pecified		
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	<b>BV</b> <sub>DSS</sub>	30	—		V	$I_D = 250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			0.5	μA	$V_{DS}$ = 30V, $V_{GS}$ = 0V	
Gate-Source Leakage	I <sub>GSS</sub>		_	±100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0		3.0	V	$I_D=250\mu A, V_{DS}=V_{GS}$	
Static Drain Source On Resistance (Note 8)	<b>D</b>		_	0.028	0	V <sub>GS</sub> = 10V, I <sub>D</sub> = 6.0A	
Static Drain-Source On-Resistance (Note 8)	RDS (ON)			0.045	12	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4.9A	
Forward Transconductance (Notes 8 & 9)	<b>g</b> fs		12		S	V <sub>DS</sub> = 15V, I <sub>D</sub> = 6.0A	
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	_	0.68	1.2	V	I <sub>S</sub> = 1.7A, V <sub>GS</sub> = 0V	
Reverse recovery time (Note 9)	t <sub>rr</sub>		11.5		ns		
Reverse recovery charge (Note 9)	Qrr		4.4		nC	$T_{S} = 1.7A$ , di/dt= 100A/µs	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss		472		pF		
Output Capacitance	Coss		178		pF	$V_{DS}$ = 15V, $V_{GS}$ = 0V f- 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		65		pF		
Total Gate Charge	Qg		5.2		nC	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 4.5V I <sub>D</sub> = 6A	
Total Gate Charge	Qg		10.5		nC		
Gate-Source Charge	Q <sub>gs</sub>		1.86		nC	$V_{DS}$ = 15V, $V_{GS}$ = 10V	
Gate-Drain Charge	Q <sub>gd</sub>	_	2.3	_	nC	ID= 0A	
Turn-On Delay Time (Note 10)	t <sub>D(on)</sub>		2.5	_	ns		
Turn-On Rise Time (Note 10)	tr		3.1	_	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V	
Turn-Off Delay Time (Note 10)	t <sub>D(off)</sub>		14		ns	$I_{D}\text{= 1A, }R_{G}\cong 6.0\Omega$	
Turn-Off Fall Time (Note 10)	t <sub>f</sub>		9.7		ns	]	

 Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures. Notes:





### Q1 N-Channel





## **Q1 N-Channel continued**



## Test Circuits – Q1 N-Channel



Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

#### Switching time test circuit

V<sub>DS</sub> 90%

10% V<sub>GS</sub>

l **←** l t<sub>d(on)</sub>

t<sub>r</sub>

t<sub>(on)</sub>

 $V_{\text{dd}}$ 





Electrical Characteristics – Q2 P-Channel @T <sub>A</sub> = 25°C unless otherwise specified								
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS				•				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	_	_	V	I <sub>D</sub> = -250μA, V <sub>GS</sub> = 0V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-0.5	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V		
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V		
ON CHARACTERISTICS								
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1.0	_	-3.0	V	I <sub>D</sub> = -250μA, V <sub>DS</sub> = V <sub>GS</sub>		
Statia Drain Source On Resistance (Note 9)	Р		_	0.025	0	V <sub>GS</sub> = -10V, I <sub>D</sub> = -7.1A		
Static Drain-Source On-Resistance (Note 8)	RDS (ON)	_		0.041	12	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5.5A		
Forward Transconductance (Notes 8 & 9)	<b>g</b> fs	_	18.6	_	S	V <sub>DS</sub> = -15V, I <sub>D</sub> = -7.1A		
Diode Forward Voltage (Note 8)	V <sub>SD</sub>		-0.80	-1.2	V	I <sub>S</sub> = -1.7A, V <sub>GS</sub> = 0V		
Reverse recovery time (Note 9)	t <sub>rr</sub>		16.2	_	ns			
Reverse recovery charge (Note 9)	Q <sub>rr</sub>	_	10	_	nC	$-1_{S}$ = -2.2A, dl/dt= 100A/µS		
DYNAMIC CHARACTERISTICS (Note 9)								
Input Capacitance	C <sub>iss</sub>	_	1678	_	pF			
Output Capacitance	C <sub>oss</sub>	_	303	_	pF	$V_{DS} = -15V, V_{GS} = 0V$		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	178	_	pF			
Total Gate Charge	Qg	_	16.4	_	nC	V <sub>DS</sub> = -15V, V <sub>GS</sub> = -4.5V I <sub>D</sub> = -7.1A		
Total Gate Charge	Qg		31.6	_	nC			
Gate-Source Charge	Q <sub>gs</sub>		4.3	_	nC	$V_{DS}$ = -15V, $V_{GS}$ = -10V		
Gate-Drain Charge	Q <sub>gd</sub>	_	6.2		nC	-1D= -7.1A		
Turn-On Delay Time (Note 10)	t <sub>D(on)</sub>		3.5	—	ns			
Turn-On Rise Time (Note 10)	tr	_	4.9	_	ns	V <sub>DD</sub> = -15V, V <sub>GS</sub> = -10V		
Turn-Off Delay Time (Note 10)	t <sub>D(off)</sub>	—	44	—	ns	$I_D$ = -1A, $R_G \cong 6.0\Omega$		
Turn-Off Fall Time (Note 10)	t <sub>f</sub>	_	28	—	ns	7		

Notes:

Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures.





## Q2 P-Channel





## **Q2 P-Channel continued**



#### **Test Circuits – Q2 P-Channel**







Gate charge test circuit



Switching time waveforms



Switching time test circuit



## **Package Outline Dimensions**



DIM	Inc	hes	Millin	neters	s DIM Inches		Millimeters		
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
А	0.053	0.069	1.35	1.75	е	0.050 BSC		1.27 BSC	
A1	0.004	0.010	0.10	0.25	b	0.013 0.020		0.33	0.51
D	0.189	0.197	4.80	5.00	С	0.008	0.010	0.19	0.25
н	0.228	0.244	5.80	6.20	θ	0°	8°	0°	8°
E	0.150	0.157	3.80	4.00	h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27	-	-	-	-	-

## Suggested Pad Layout





#### DMC3028LSD

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